

APPENDIX A: CLAIMS ON APPEAL (S/N 09/924,711)

1. - 10. (Canceled)
11. (Once Amended) An assembly comprising:
a circuit board;
an area array bonding site on a surface of the circuit board; and
a protective cover overlaying the bonding site, the protective cover being non-conductive throughout at least a region thereof that overlays the bonding site, and the protective cover removably registered to the bonding site by a plurality of posts secured to one of the protective cover and the circuit board into a plurality of apertures disposed in the other of the protective cover and the circuit board.
12. (Unchanged) The assembly of claim 11, wherein the protective cover includes an adhesiveless surface contacting the bonding site.
13. - 18. (Canceled)
19. (Once Amended) A cover for protecting an area array bonding site on a surface of a circuit board, the circuit board having a plurality of apertures, the cover comprising:
a base member having a first face and second face, the base member shaped to at least correspond to said area array bonding site, and the base member being non-conductive throughout at least a region thereof that is configured to overlay the bonding site; and
a plurality of posts coupled to the first face and registered for said plurality of apertures.
20. (Unchanged) The cover of claim 19, wherein the first face of the base member further includes a recess corresponding to said area array bonding site.
21. (Unchanged) The cover of claim 19, further comprising:
a graspable extension coupled to the second face of the base member.

22. (Unchanged) The cover of claim 19, wherein each of the plurality of posts includes a diametral slot.

23. (Added) The assembly of claim 11, wherein the plurality of posts are secured to the protective cover, and wherein the plurality of apertures are disposed in the circuit board.

24. (Added) The assembly of claim 11, wherein the protective cover is formed of a non-conductive material.

25. (Added) The assembly of claim 24, wherein the protective cover is formed of epoxy glass.

26. (Added) The assembly of claim 11, further comprising a graspable extension disposed on a surface of the protective cover opposite that which overlays the bonding site.

27. (Added) The assembly of claim 11, wherein each of the plurality of posts includes a diametral slot.

28. (Added) The assembly of claim 11, wherein the protective cover has a thickness of about 0.006 to about 0.008 inches.

29. (Added) The assembly of claim 11, wherein the protective cover further includes a recess overlaying the bonding site.

30. (Added) The cover of claim 19, wherein the base member is formed of a non-conductive material.

31. (Added) The cover of claim 30, wherein the base member is formed of epoxy glass.

32. (Added) The cover of claim 19, wherein the base member has a thickness of about 0.006 to about 0.008 inches.